



LANGUAGE

English

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1.0 SCOPE

This specification defines the performance for theof the 2.54 mm pitch SIM pcb connector 91228, and mating card holders 91236 and 91356 for usage with the Plug-in SIM as specified by the GSM 11.11 Version 5.3.0: July 1999 specification.

NOTE: Normal force at maximum deflection see Test Ref. 5.10.

2.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

See sales drawing and other sections of this specification for the relevant reference documents and specifications. In cases where the specification differs from the product drawings, the product drawings take precedence.

Description	Document
SIM pcb connector	SDA-91228
Card Holder	SDA-91236 SD-91356-001

3.0 RATINGS

3.1	Current	0.5 Amp maximum per contact
3.2	Voltage	50 V DC (maximum)
3.3	Durability	5000 mating cycles
3.4	Operating temperature range	-30°C to +85°C
3.5	Storage temperature range	-40°C to +90°C

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4.0 ELECTRICAL PERFORMANCE

See section 7.0 for test sequence.

Test	Item	Test Condition	Requirements
Ref.			
4.1.	Contact Resistance	Mated connector with	Initial Value <50mΩ
	(IEC 512-2,test2a)	dry circuit of 20mV,	
		100mA maximum, per	
		Appendix 1	
4.2	Insulation Resistance	Unmated connector	$1000~\mathrm{M}\Omega$ minimum
	(IEC 512-2,test 3a)	with 500 V DC	
		between adjacent	
		contacts	
4.3	Dielectric Strength	Unmated connector	No voltage breakdown
	(IEC 512-2,test 4a)	with 1000 V AC for 1	
		minute between	
		adjacent contacts, as	
		per Appendix 2	

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5.0 MECHANICAL PERFORMANCE

5.1 Durability Mate connector card inserted in I rate of 10 cycles to 5000 cyc. Use push button ejection, as per A 5.2 Vibration (IEC 68-2-6) Shock (IEC 68-2-6) 5.3 Shock (IEC 68-2-27) 5.4 Solder Tab Destruction Test Destruction Test Mate connector of 25 ± 3 mm 5.6 Unmating Force Total 18 shows a shock seach of 25 ± 3 mm 5.7 Card Holder Retention Force (latch enabled) 5.8 Terminal/Housing Retention Force Apply a 4.9 N I min in all directing Appendix Mate connector of 25 ± 3 mm Pull card holder 25-50 mm/ Apply an axial terminal assemble housing at a seach of 25-50 mm/min	ition Requirements	Test Condition	Item	Test Ref.
5.2 Vibration (IEC 68-2-6) Shock (IEC 68-2-27) 5.3 Shock (IEC 68-2-27) Shocks each of X total 18 shocks each of X total	holder at a per minute cles. damage. Maximum change from initial contact resistance = $20m\Omega$	Mate connector with SIM card inserted in holder at a rate of 10 cycles per minute to 5000 cycles. Use push button for card ejection, as per Appendix 3	Durability	
5.4 Solder Tab Destruction Test Mating Force 5.5 Mating Force Mate connector of 25 ± 3 mm 5.6 Unmating Force Unmate connector of 25 ± 3 mm 5.7 Card Holder Retention Force (latch enabled) 5.8 Terminal/Housing Retention Force Apply a 4.9 N I min in all directi Appendix Mate connector of 25 ± 3 mm Pull card holder 25-50 mm/ Apply an axial terminal assemble housing at a s 25-50mm/min	mm or 2g, <1µsecond discontinuity.	10-150 Hz 0.15mm or 2g, duration 40 minutes, total 5 cycles in X,Y,Z axes		5.2
Destruction Test min in all directing Appendix 5.5 Mating Force Mate connectors of 25 ± 3 mm 5.6 Unmating Force Unmate connector of 25 ± 3 mm 5.7 Card Holder Retention Force (latch enabled) Pull card holder 25-50 mm/ 5.8 Terminal/Housing Apply an axial terminal assemble housing at a semble 25-50mm/min	,Y,Z axes, discontinuity.	50g/11m sec ½ Sine, 3 shocks each of X,Y,Z axes, total 18 shocks		5.3
5.5 Mating Force Mate connector of 25 ± 3 mm 5.6 Unmating Force Unmate connector of 25 ± 3 mm 5.7 Card Holder Retention Force (latch enabled) 7.8 Terminal/Housing Retention Force Retention Force Apply an axial terminal assemble housing at a separation at a separation process.	ons, as per joints (cracks or	Apply a 4.9 N load for 1 min in all directions, as per Appendix 4		5.4
5.7 Card Holder Retention Force (latch enabled) 5.8 Terminal/Housing Retention Force Retention Force Solution Force Terminal Apply an axial terminal assemble housing at a second content of the cont	s at a rate Mating Force 4.9 N	Mate connectors at a rate of 25 ± 3 mm/min	Mating Force	5.5
Force (latch enabled) 5.8 Terminal/Housing Retention Force Apply an axial terminal assemble housing at a second	C \1	Unmate connectors at a rate of 25 ± 3 mm/min	Unmating Force	5.6
Retention Force terminal assemble housing at a s 25-50mm/min	•	Pull card holder axially at 25-50 mm/min.		5.7
Contd. next page	pled in the min peed of a, as per	Apply an axial load to a terminal assembled in the housing at a speed of 25-50mm/min, as per Appendix 5	Terminal/Housing Retention Force	5.8

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Test	Item	Test Condition	Requirements
Ref.			
5.9	Multi-axis Function Test	Apply Forces in all 4	F1/F2/F3/F4/F5>40N
	for PCB Mounted Housing.	directions, as per Appendix	
		6	
5.10	Normal Force at maximum	Measure Normal Force at	Maximum Normal
	deflection	maximum deflection shown	Force ≤ 0.7 N.
		in Appendix 8	

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6.0 ENVIRONMENTAL PERFORMANCE

Test	Item	Test Condition	Requirements
Ref.			
6.1	Resistance to solder	a) Sample to be passed	Appearance - no
	conditions	twice through reflow oven	damage
		according to temp profile	
		shown in appendix 7. One	
		hour cooling between	
		passes.	
		b) Manual soldering at	
		solder temp. of 300±5°C	
		for 3 sec.	
6.2	Solderability	Samples to be steam aged	95% of immersed area
	(IEC 68-2-20, test Ta,	for 16 hrs using a steam	must show no voids, pin
	method 1)	aging chamber, or	holes, etc.
		equivalent.	
		Solder temp. 235±5°C,	
		wetting time 3 sec.	
6.3	Damp Heat Cyclic	Upper air temp. 25-55°C	Appearance - no
	(IEC 68-2-30, variant 1)	for 6 cycles, duration 6	damage. Maximum
		days	change from initial
		Recovery is 2 hrs at std.	contact resistance =
		atmospheric condition.	20mΩ
6.4	Salt Spray	5+/-1% salt solution	Appearance - no
	(IEC 512-6 ,test 11f)	Duration 48 hrs	damage. Maximum
			change from initial
			contact resistance =
			$20 \mathrm{m}\Omega$
6.5	Long Term Dry Heat	105°C for 1000 hours	Appearance - no
			damage. Maximum
			change from initial
			contact resistance =
			$20 \mathrm{m}\Omega$
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Test Ref.	Item	Test Condition	Requirements
6.6	Temperature Change (IEC 68-2-14)	Ta = -30°C, Tb =85°C, rate of change of temperature 1±0.2 C /minute 8 hours/cycle for 5 cycles Recovery is 2 hrs at std. atmospheric condition.	Appearance - no damage. Maximum change from initial contact resistance = $20\text{m}\Omega$
6.7	Thermal Shock (IEC 68-2-14)	-40°C to +85°C 5 cycles per hour (total 5 hours)	Appearance - no damage. Maximum change from initial contact resistance = $20m\Omega$
6.8	SO ₂ (IEC 68-2-42-KC)	Mated connectors exposed to 10 ±3ppm of SO ₂ gas with 85-90% humidity at 40 ±2°C for 96 hours.	Appearance - no damage. Maximum change from initial contact resistance = $20m\Omega$
6.9	Temperature Rise Test	Mate connector and measure the temperature rise of the contacts when the max. rated DC current is applied	Temperature rise of 30 °C max
6.10	Cold Resistance	Mate connectors and expose to -40 ±3°C for 96 hours. Allow samples to reach room temp (1hr) before measurement.	Appearance - no damage. Maximum change from initial contact resistance = $20m\Omega$
6.11	Heat Resistance	Mate connectors and expose to $85 \pm 2^{\circ}$ C for 96 hours. Allow samples to reach room temp (1hr) before measurement.	Appearance - no damage. Maximum change from initial contact resistance = $20\text{m}\Omega$

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7.0 TEST GROUPINGS

Test Ref.	Test Item	GP1	GP2	GP3	GP4	GP5
4.1	Contact Resistance	2,4,6	2,8,12	2,4,6,8	2,4,6	
4.2	Insulation Resistance		5,13			
4.3	Dielectric Strength		6,14			
5.1	Durability		7			
5.2	Vibration					
5.3	Shock				5	
5.4	Solder Tab Destructioon Test.					2
5.5	Mating Force.		3,10			2
5.6	Unmating Force.		4,9			
5.7	Card Retention Force.					2
5.8	Terminal/Housing Retention					2
	Force					
5.9	Multiaction Function Test for					2
	PCB Mounted Housing					
5.10	Normal Force at maximum	3,7				
	deflection					
6.1	Resistance to Solder Conditions	1	1	1	1	1
6.2	Solderability					2
6.3	Damp Heat Cyclic		11			
6.4	Salt Spray			5		
6.5	Long Term Dry Heat	5				
6.6	Temp. Change				3	
6.7	Thermal Shock			3		
6.8	SO_2				7	
6.9	Temperature Rise					2
6.1	Cold Resistance			7		
6.11	Heat Resistance					2

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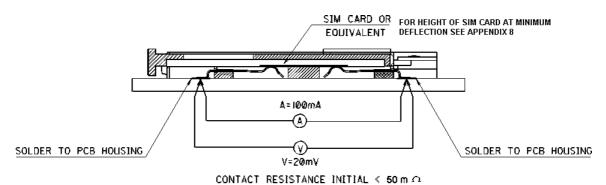




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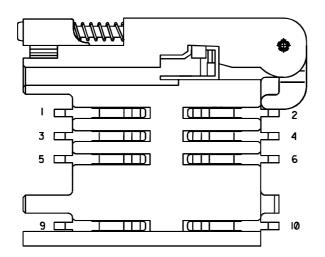
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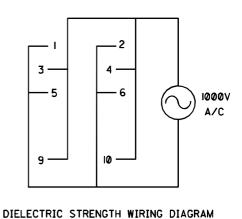
Appendix 1:



Contact Resistance Measurement (4.1)

Appendix 2:





Dielectric Strength (4.3)

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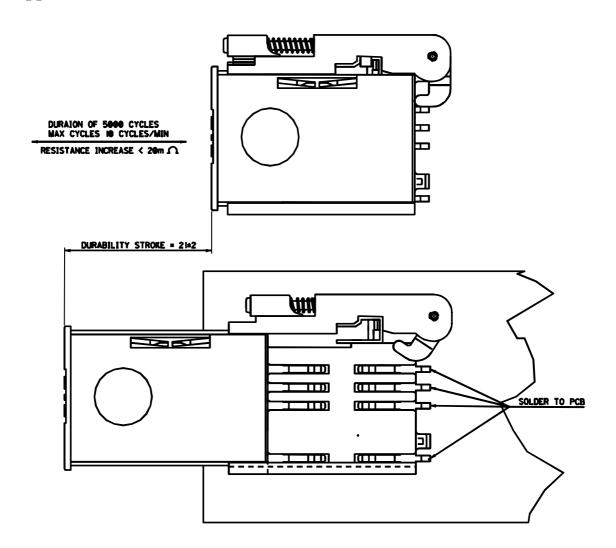




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Appendix 3:



Durability (5.1)

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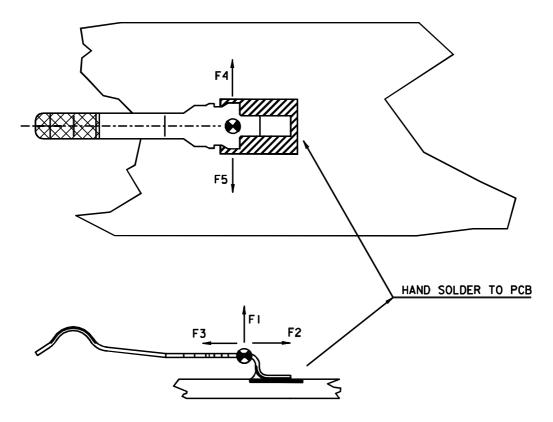




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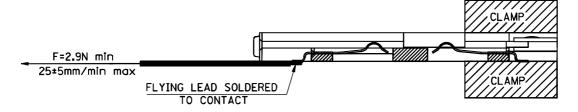
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Appendix 4:



Solder Tab Destruct Test (5.4)

Appendix 5:



Terminal/Housing Retention Force (5.8)

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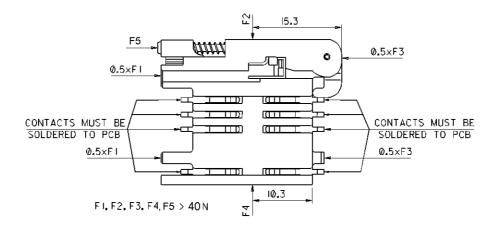




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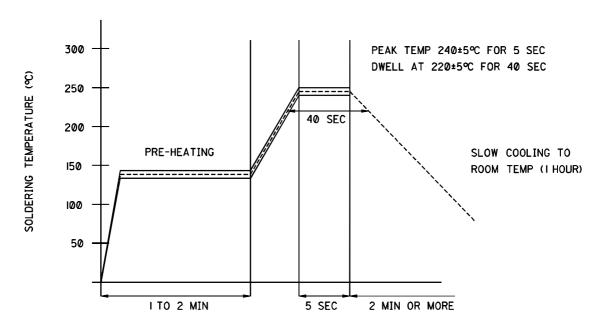
Appendix 6:



Mulitaxis Function Test (5.9)

Appendix 7:

REFLOW SOLDERING TEMPERATURE PROFILE



Resistance to Solder Conditions (6.1)

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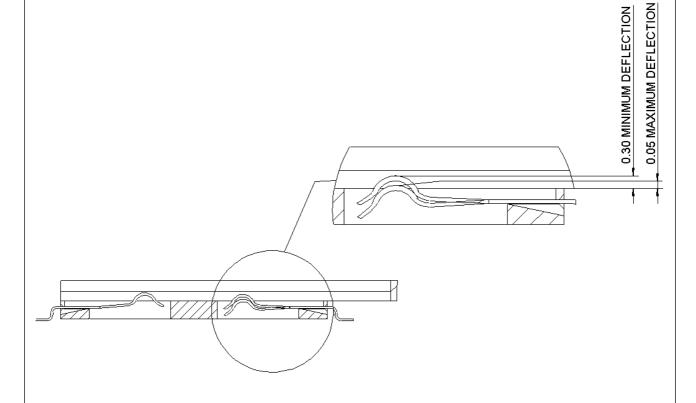




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Appendix 8:



Maximum Normal Force (5.10)

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